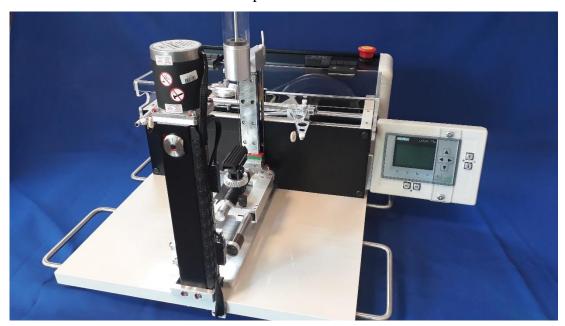
## PRINCETON SCIENTIFIC CORP.

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## Wire Saw WS-25B

WS-25B is the newest high precision wire saw in our product line. This unique saw can cut using the free abrasive method (wet cut), as well as cut using diamond dotted wire (dry cut). A digitally controlled vertical axis is responsible for feeding the specimen during the cutting process. Vertical movement of the sample is 0.3µm per step of motor. This solution keeps the frame with wire at the same level throughout the cutting process. The WS-25 wire saw has been developed to meet two important requirements: cutting should not introduce deformations or defects, and losses of material should be minimized.

The wire saw enables cutting of very thin slices (thickness of  $10\mu m$ ) with smooth cut surfaces. The use of the special accessories (goniometers, orientation devices) extends the WS25B saw's application to precision cutting of crystallographic oriented crystals.

## **ADVANTAGES**

- \* Semi-automatic, requires no supervision
- \* Can cut semiconductors, ferrites, metals,
- \*Minimized material losses (>30 um) glasses and other hard or brittle solids
- \*slices samples perfectly parallel
- \* No additional lapping required
- \* Can be used with accessories to extend the saw's application in precision cutting

## **TECHNICAL DATA**

- \* Sample max dimensions: 80mm x80mm,
- \* Power Supply: 220-250 V/50 Hz or 110 V/60- Hz
- \* Tungsten wire diameter: 20-60 µm
- \* Diamond dotted wire: 100-300 µm
- \* Wire oscillation frequency: 150-200/min
- \* Weight: 68 kg
- \* Dimensions: 630 x 720 x 250 mm